

## ERRATUM

# 3D-printed microelectronics for integrated circuitry and passive wireless sensors

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Since the publication of this article, the authors would like to make two corrections in the third(last) paragraph of “Design and Fabrication” section as follows:

- 1 Replace “fused deposition modeling technology” with “multi-jet modeling (MJM)”;
- 2 The company information of “ProJet HD 3000 printer, Hewlett-Packard Company, Palo Alto, CA, USA” should be replaced with “ProJet HD 3000 printer, 3D Systems Inc., Rock Hill, SC, USA”.

We apologize for any inconvenience may have caused.